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**REMARKS**

Claims 1-6 and 9-20 are pending. Claims 19 and 20 are new. The Applicant respectfully requests reconsideration and allowance of this application in view of the above amendments and the following remarks.

Initially, the Applicant requests that the Examiner withdraw the finality of the present rejection. MPEP 706.07(a) states: "Under present practice, second or any subsequent actions on the merits shall be final, except where the examiner introduces a new ground of rejection that is neither necessitated by applicant's amendment of the claims nor information submitted in an information disclosure statement filed during the period set forth in 37 CFR 1.17(p)."

In the present application, the Applicant only amended one claim for cosmetic purposes and added new claims 12-18 in the previous amendment filed on May 27, 2003 that was responsive to the Examiner's rejection of claims 1-6 and 9-11 in view of Nagahara and Yoshihara in the Office Action dated March 10, 2003. However, the Examiner again rejected claims 1-6 and 9-11, as well as claims 12-16 and 18, based on Nagahara and Tsukagoshi, which was substituted for Yoshihara, in the Final Rejection dated December 31, 2003. As the Applicant did not necessitate the Final Rejection through either previous claim amendments or a supplemental information disclosure statement, they respectfully assert that the finality of the present rejection is improper per MPEP 706.07(a) and that it be withdrawn.

Claims 1-6, 9-11 and 18 have been rejected under 35 U.S.C. § 103(a) as being unpatentable over U.S. Patent No. 6,323,529 to Nagahara in view of U.S. Patent No. 5,843,251 to Tsukagoshi et al.. This rejection is respectfully traversed.

Newly amended claims 1 and 9 recite the semiconductor dynamic sensor shown, for example, in FIGS. 1 and 2 and described on page 6, line 17 through page 7, line 8. The

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semiconductor dynamic sensor of the present invention includes a sensor chip 5 with moveable electrodes 54 on one surface of a sensor chip that are displaced relative to the fixed electrodes 55 in response to an acceleration or deceleration force, and has another surface that is attached to a substrate 3 by a film, such as, for example, an adhesive film 4. The adhesive film 4 prevents misalignment of the sensor chip 5 on the substrate 3 that might otherwise occur if a die bond resin or an adhesive agent is used as shown in FIGS. 4A and 4B. Put another way, the adhesive film enables the sensor chip to be more precisely positioned on a substrate than if a die bond resin or adhesive agent is used because the resin or adhesive tends to flow during curing and therefore causes the sensor chip to move (i.e. lift up or rotate) relative to the circuit board during curing.

Nagahara discloses a semiconductor acceleration sensor in which a signal-processing chip 5 is mounted on an acceleration sensor chip 3, with the acceleration sensor chip 3 being connected to a die pad 11 by a die bond resin 13. However, Nagahara neither teaches nor suggests (1) a moveable member on one surface of the acceleration sensor chip 3, or (2) another surface of the sensor chip being connected to a substrate using an adhesive film.

The Examiner cites Tsukagoshi to cure the deficiencies of Nagahara, and namely because Tsukagoshi allegedly discloses an adhesive layer formed by spreading the adhesive layer in the form of a film. Tsukagoshi discloses a process for connecting circuits with improved connection reliability and workability. More particularly, Tsukagoshi discloses forming a layer of adhesive 5 between electrodes 2 projecting from the main face 6 of an electric part and the circuits 4 provided on an insulating substrate 3, and positioning the connecting points of the projecting electrodes 2 and the corresponding circuits 4 (col. 4, lines 38-45). However,

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Tsukagoshi neither teaches nor suggests an acceleration sensor chip with a moveable member on one surface and another surface connected to the substrate by an adhesive film.

Therefore, because neither Nagahara nor Tsukagoshi, either singly or in combination, teaches or suggests a sensor chip that includes one surface with a moveable member and that includes another surface connected to a substrate by an adhesive film, the Applicant respectfully requests that the Examiner's rejection of claims 1 and 9, as well as dependent claims 2-6 and 10-11 be withdrawn.

Claim 12, which recites similar limitations of allowable claims 1 and 9, is believed to be allowable for the reasons discussed above. Therefore, the Applicant respectfully request the 35 U.S.C. 103(a) rejection of claim 12, as well as dependent claims 13-16 and 18, be withdrawn.

The Applicant notes with appreciation the Examiner's indication that claim 17 contains allowable subject matter and would be allowable if rewritten in independent form, including all of the limitations of the base claim and any intervening claims. Claim 17 has been rewritten in independent form and is now believed to be allowable.

Newly submitted claim 19, by reciting a semiconductor dynamic sensor with a thickness of the adhesive film that is less than 50  $\mu\text{m}$ , is believed to be allowable for at least the reasons set forth here within. Support for claim 19 can be found on page 7, lines 9-10 of the specification. Favorable consideration is requested.

Newly submitted claim 20, by reciting a semiconductor dynamic sensor with an elasticity coefficient of the adhesive film is that less than 3,000 mega Pascals, is believe to be allowable for at least the reasons set forth here within. Support for claim 20 can be found on page 3, lines 18-21. Favorable consideration is requested.

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As the application is in condition for allowance for the above stated reasons, Applicant respectfully requests that the Examiner issue a Notice of Allowance as soon as possible.

Permission is hereby given to charge any unanticipated fees to Deposit Account No. 50-1147.

Respectfully submitted,



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